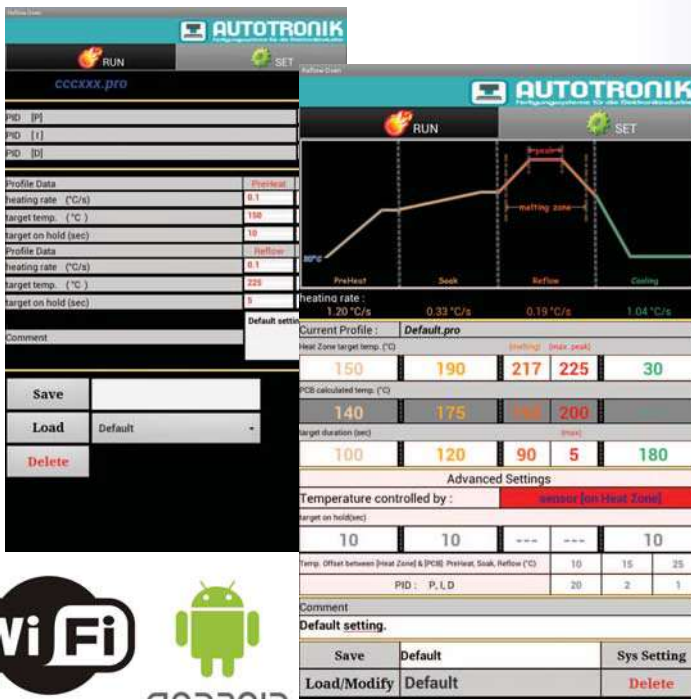


# Bench-top / Batch Reflow Oven

## BT301

Dynamic Thermal Profile using a Batch Reflow Oven with Android™ Operating System

Match your thermal process specifications for preheat, soak, reflow, and cooling on the first PCB you produce with by using revolutionary new BT301 Batch Reflow Oven. Having the thermal conditions of an inline reflow system in a bench-top unit with a full dynamic thermal process.

Profile Data	Preheat
heating rate (°C/s)	0.1
target temp. (°C)	150
target on hold (sec)	10
Profile Data	Reflow
heating rate (°C/s)	0.1
target temp. (°C)	220
target on hold (sec)	5

Current Profile	Default pro
Heat Zone target temp. (°C)	(heating) (soak) (reflow) (cool)
150	190 217 225 30
PCB calculated temp. (°C)	140 175 190 200
target duration (sec)	100 120 90 5 180

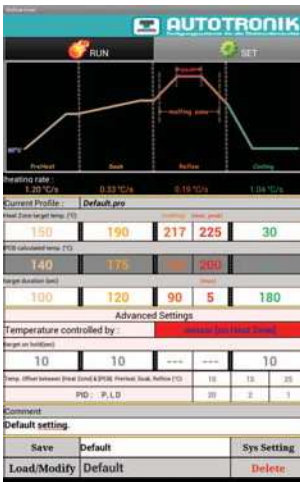
Advanced Settings				
Temperature controlled by: sensor (on Heat Zone)				
target on hold(sec)	10	10	---	10
Temp. Offset between (Heat Zone) & (PCB) Preheat, Soak, Reflow (°C)	10	15	25	
PID: P, I, D	20	2	1	



The BT301 is ideal for product development, prototyping, and small series production. Solder profiles are easily set-up and stored through the control app of the BT301's exclusive hardware control and Android operating system. The dynamic control system takes care of size and complexity of your assembly and makes it a closed loop process, something only large and costly thermal systems can normally offer.

## Features

- ⊙ Real time close loop PID temperature control for leadfree profile
- ⊙ Quick Smart programming by rising rate control (degree change per second)
- ⊙ Infrared and forced convection combine for efficient lead-free reflow
- ⊙ Real time temperature profile display
- ⊙ Android system on multi-core CPU platform
- ⊙ 7" touch screen high resolution LCD display
- ⊙ Compact design ideal for labs, schools, prototyping and low-volume job shops
- ⊙ WiFi temperature profile printing and data storage



## Real-Time dynamic thermal Control via On-Board measuring device

The BT301 has an advanced setting in which you can turn on the real time dynamic process. The unit can then via real-time feedback from the measuring system which is attached at a strategic location on the PCB surface.

The heater control and fan speed is based on the actual temperature measured on the product. The target temperature is equal to the dynamic measuring system temperature and there is no offset, making this a perfect tool for prototyping and small series.

## Specification

### Machine Model

Applicable solder types  
 PCB holding size  
 PCB effective heating area  
 Heating method  
 Temperature range  
 Temperature control method

Warm-up time  
 Computer control  
 Display panel  
 Temperature control setting

Temperature profile display  
 Temp profile printing  
 Storage  
 Electrical  
 Power  
 Dimensions  
 Weight

### BT301

Lead-Free and Leaded  
 350 mm x 240 mm  
 250 mm x 200 mm  
 Quartz IR & Forced Hot Air Convection  
 Ambient - 310 °C  
 Real time close loop PID temperature control for lead free profile approx. 2 min.  
 Build-in dual core CPU on board computer  
 7" touch screen high resolution LCD display  
 Quick smart profile programming by temperature rising rate control (degree change per second)  
 Real time temperature profile display  
 WiFi temperature profile printing  
 External data storage via WiFi connection  
 220 V, Single Phase, 50/60 Hz, 15A  
 3000W  
 690 mm L x 470 mm W x 270 mm H  
 approx. 45 Kg

\* We reserve the right to make changes without notice.